

<p style="text-align: center;">Substitute for FORM PTO-1449 U.S. Department of Commerce Patent and Trademark Office INFORMATION DISCLOSURE STATEMENT BY APPLICANT <small>(Use several sheets if necessary)</small></p> <p style="text-align: center;">JUN 14 2002 O I P E PATENT AND TRADEMARK OFFICE U.S. DEPARTMENT OF COMMERCE</p>					Application Number	10/081,074
					Filing Date	2/12/2002
					First Named Inventor	Sergey Lopatin
					Attorney Docket No.	P1406
U.S. PATENT DOCUMENTS						
Examiner Initial	Cite No.	U.S. Patent Document Number	Name of Patentee or Applicant of Cited Documents	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
8Y	1	6,197,181 B1	Chen, Lin Lin	3/6/2001		
8Y	2	6,022,808	Nogami, et al.	2/8/2000		
FOREIGN PATENT DOCUMENTS						
Examiner Initials'	Cite No.	Foreign Patent Document Office Number Code	Name of Patentee or Applicant of Cited document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appears	
OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS						
Examiner Initials'	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.				
8Y	1	PETER VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing", 3 rd Ed., p. 392 and 397 (1997)				
8Y	2	A. Krishnamoorthy, D. Duquette and S. Murarka, "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization", in edited by Adricacos, et al., Electrochem Society Symposium Proceedings, Vol. 99-9, May 3-6, Seattle, p. 212 (date unknown)				
8Y	3	J. Cunningham, "Using Electrochemistry to Improve Copper Interconnect", in Semiconductor International, Spring 2000 (May)				
8Y	4	L. Chen and T. Ritzdorf, "ECD Seed Layer for Inlaid Copper Metallization" in edited by Andricacos, et al., Electrochem Society Proceedings, Vol. 99-9, May 3-6, Seattle, p. 122 (date unknown)				
Examiner Signature: <i>Stoyanoff</i>			Date Considered: 4/1/03			
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>						

¹Unique citation designation number. ²See attached Kinds of U.S. Patent Documents. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶Applicant is to place a check mark here if English Language Translation is attached.